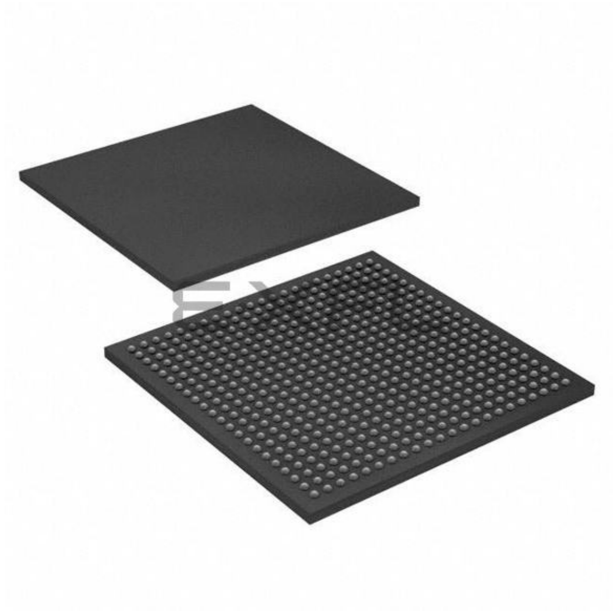
Intel - 5CSEBA2U19C7SN Datasheet



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Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems

Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are Embedded - System On Chip (SoC)?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions, SoCs combine a central

Details	
Product Status	Active
Architecture	MCU, FPGA
Core Processor	Single ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	64KB
Peripherals	DMA, POR, WDT
Connectivity	CANbus, EBI/EMI, Ethernet, I²C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	800MHz
Primary Attributes	FPGA - 25K Logic Elements
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-FBGA
Supplier Device Package	484-UBGA (19x19)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5cseba2u19c7sn

Cyclone V Device Overview

The Cyclone® V devices are designed to simultaneously accommodate the shrinking power consumption, cost, and time-to-market requirements; and the increasing bandwidth requirements for high-volume and cost-sensitive applications.

Enhanced with integrated transceivers and hard memory controllers, the Cyclone V devices are suitable for applications in the industrial, wireless and wireline, military, and automotive markets.

Related Information

Cyclone V Device Handbook: Known Issues
Lists the planned updates to the Cyclone V Device Handbook chapters.

Key Advantages of Cyclone V Devices

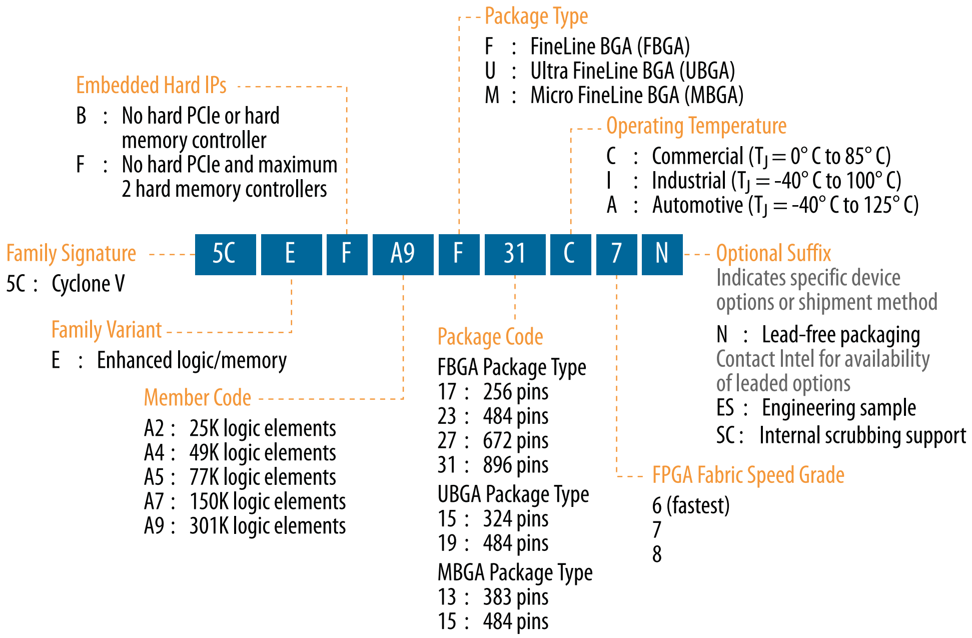
Table 1. Key Advantages of the Cyclone V Device Family

Advantage	Supporting Feature
Lower power consumption	• Built on TSMC's 28 nm low-power (28LP) process technology and includes an abundance of hard intellectual property (IP) blocks • Up to 40% lower power consumption than the previous generation device
Improved logic integration and differentiation capabilities	• 8-input adaptive logic module (ALM) • Up to 13.59 megabits (Mb) of embedded memory • Variable-precision digital signal processing (DSP) blocks
Increased bandwidth capacity	• 3.125 gigabits per second (Gbps) and 6.144 Gbps transceivers • Hard memory controllers
Hard processor system (HPS) with integrated Arm* Cortex*-A9 MPCore* processor	• Tight integration of a dual-core Arm Cortex-A9 MPCore processor, hard IP, and an FPGA in a single Cyclone V system-on-a-chip (SoC) • Supports over 128 Gbps peak bandwidth with integrated data coherency between the processor and the FPGA fabric
Lowest system cost	• Requires only two core voltages to operate • Available in low-cost wirebond packaging • Includes innovative features such as Configuration via Protocol (CvP) and partial reconfiguration

Available Options

Figure 1. Sample Ordering Code and Available Options for Cyclone V E Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.



Family Signature
5C : Cyclone V

Embedded Hard IPs
B : No hard PCIe or hard memory controller
F : No hard PCIe and maximum 2 hard memory controllers

Family Variant
E : Enhanced logic/memory

Member Code
A2 : 25K logic elements
A4 : 49K logic elements
A5 : 77K logic elements
A7 : 150K logic elements
A9 : 301K logic elements

Package Type
F : FineLine BGA (FBGA)
U : Ultra FineLine BGA (UBGA)
M : Micro FineLine BGA (MBGA)

Package Code
FBGA Package Type
17 : 256 pins
23 : 484 pins
27 : 672 pins
31 : 896 pins
UBGA Package Type
15 : 324 pins
19 : 484 pins
MBGA Package Type
13 : 383 pins
15 : 484 pins

Operating Temperature
C : Commercial (T_J = 0° C to 85° C)
I : Industrial (T_J = -40° C to 100° C)
A : Automotive (T_J = -40° C to 125° C)

FPGA Fabric Speed Grade
6 (fastest)
7
8

Optional Suffix
Indicates specific device options or shipment method
N : Lead-free packaging
Contact Intel for availability of leaded options
ES : Engineering sample
SC : Internal scrubbing support

Maximum Resources

Table 4. Maximum Resource Counts for Cyclone V E Devices

Resource		Member Code				
		A2	A4	A5	A7	A9
Logic Elements (LE) (K)		25	49	77	150	301
ALM		9,430	18,480	29,080	56,480	113,560
Register		37,736	73,920	116,320	225,920	454,240
Memory (Kb)	M10K	1,760	3,080	4,460	6,860	12,200
	MLAB	196	303	424	836	1,717
Variable-precision DSP Block		25	66	150	156	342
18 x 18 Multiplier		50	132	300	312	684
PLL		4	4	6	7	8
GPIO		224	224	240	480	480
LVDS	Transmitter	56	56	60	120	120
	Receiver	56	56	60	120	120
Hard Memory Controller		1	1	2	2	2

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices
Provides the number of LVDS channels in each device package.

Package Plan

Table 5. Package Plan for Cyclone V E Devices

Member Code	M383 (13 mm)	M484 (15 mm)	U324 (15 mm)	F256 (17 mm)	U484 (19 mm)	F484 (23 mm)	F672 (27 mm)	F896 (31 mm)
	GPIO	GPIO	GPIO	GPIO	GPIO	GPIO	GPIO	GPIO
A2	223	—	176	128	224	224	—	—
A4	223	—	176	128	224	224	—	—
A5	175	—	—	—	224	240	—	—
A7	—	240	—	—	240	240	336	480
A9	—	—	—	—	240	224	336	480

Cyclone V GX

This section provides the available options, maximum resource counts, and package plan for the Cyclone V GX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

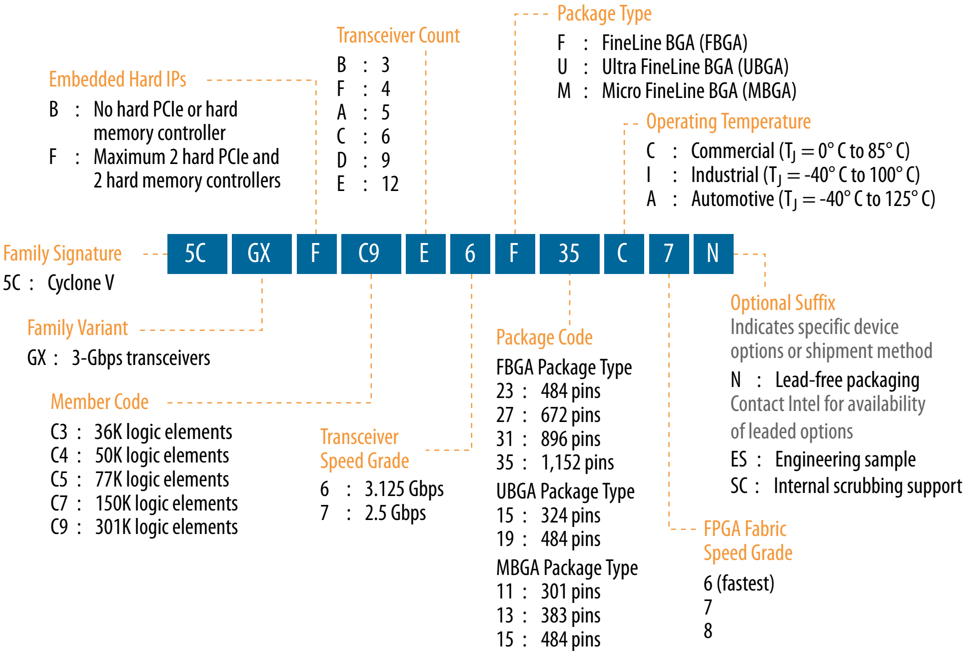
Related Information

Product Selector Guide
Provides the latest information about Intel products.

Available Options

Figure 2. Sample Ordering Code and Available Options for Cyclone V GX Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.



Maximum Resources

Table 6. Maximum Resource Counts for Cyclone V GX Devices

Resource		Member Code				
		C3	C4	C5	C7	C9
Logic Elements (LE) (K)		36	50	77	150	301
ALM		13,460	18,860	29,080	56,480	113,560
Register		53,840	75,440	116,320	225,920	454,240
Memory (Kb)	M10K	1,350	2,500	4,460	6,860	12,200
	MLAB	182	424	424	836	1,717
Variable-precision DSP Block		57	70	150	156	342
18 x 18 Multiplier		114	140	300	312	684
PLL		4	6	6	7	8
3 Gbps Transceiver		3	6	6	9	12
GPIO(4)		208	336	336	480	560

continued...

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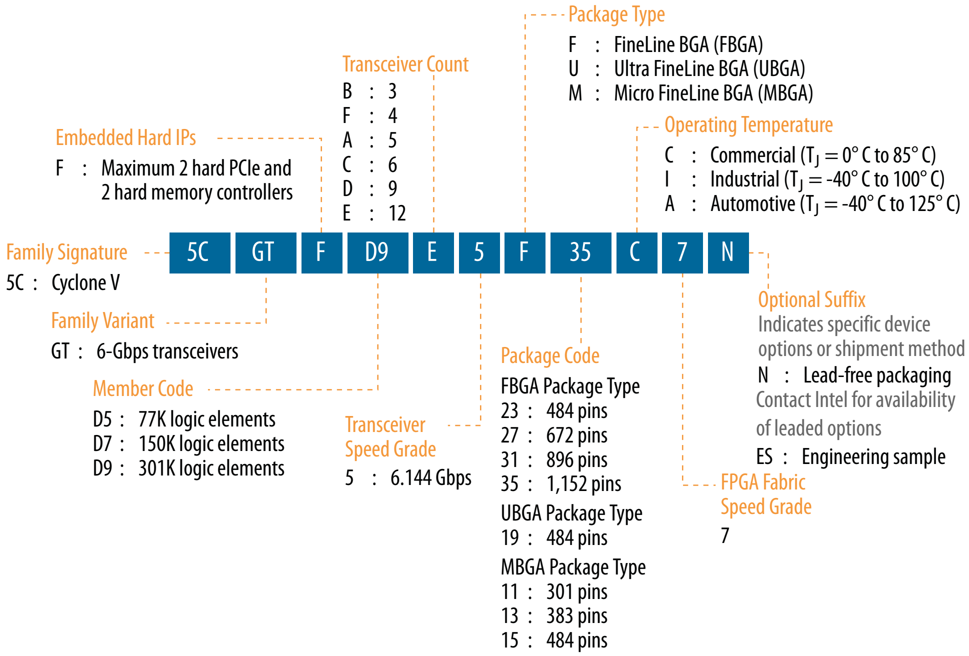
(4) The number of GPIOs does not include transceiver I/Os. In the Intel Quartus® Prime software, the number of user I/Os includes transceiver I/Os.

Available Options

Figure 3. Sample Ordering Code and Available Options for Cyclone V GT Devices



Maximum Resources

Table 8. Maximum Resource Counts for Cyclone V GT Devices

Resource		Member Code		
		D5	D7	D9
Logic Elements (LE) (K)		77	150	301
ALM		29,080	56,480	113,560
Register		116,320	225,920	454,240
Memory (Kb)	M10K	4,460	6,860	12,200
	MLAB	424	836	1,717
Variable-precision DSP Block		150	156	342
18 x 18 Multiplier		300	312	684
PLL		6	7	8
6 Gbps Transceiver		6	9	12
GPIO(5)		336	480	560
LVDS	Transmitter	84	120	140

continued...

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(5) The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

Cyclone V SE

This section provides the available options, maximum resource counts, and package plan for the Cyclone V SE devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

Related Information

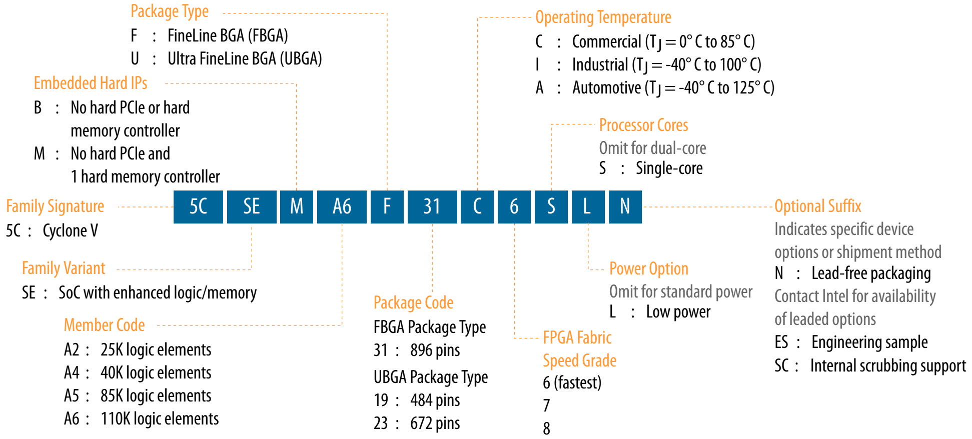
Product Selector Guide
Provides the latest information about Intel products.

Available Options

Figure 4. Sample Ordering Code and Available Options for Cyclone V SE Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Cyclone V SE and SX low-power devices (L power option) offer 30% static power reduction for devices with 25K LE and 40K LE, and 20% static power reduction for devices with 85K LE and 110K LE.



Cyclone V SX

This section provides the available options, maximum resource counts, and package plan for the Cyclone V SX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

Related Information

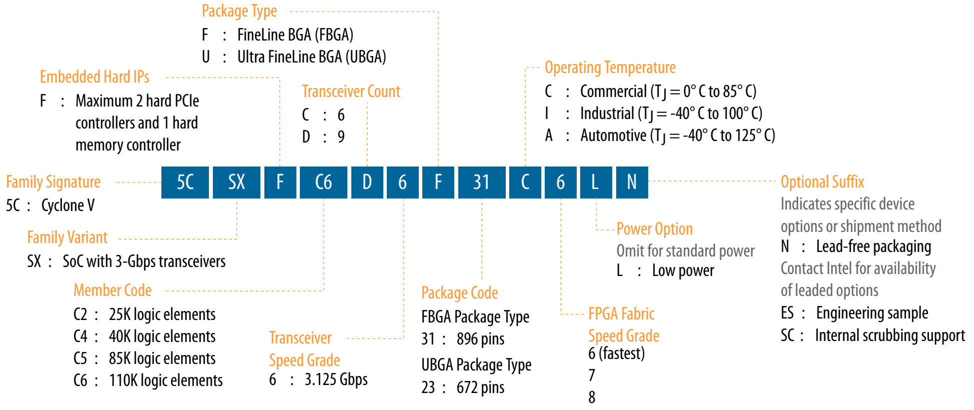
Product Selector Guide
Provides the latest information about Intel products.

Available Options

Figure 5. Sample Ordering Code and Available Options for Cyclone V SX Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Cyclone V SE and SX low-power devices (L power option) offer 30% static power reduction for devices with 25K LE and 40K LE, and 20% static power reduction for devices with 85K LE and 110K LE.



Maximum Resources

Table 12. Maximum Resource Counts for Cyclone V SX Devices

Resource		Member Code			
		C2	C4	C5	C6
Logic Elements (LE) (K)		25	40	85	110
ALM		9,430	15,880	32,070	41,910
Register		37,736	60,376	128,300	166,036
Memory (Kb)	M10K	1,400	2,700	3,970	5,570
	MLAB	138	231	480	621
Variable-precision DSP Block		36	84	87	112
18 x 18 Multiplier		72	168	174	224
FPGA PLL		5	5	6	6

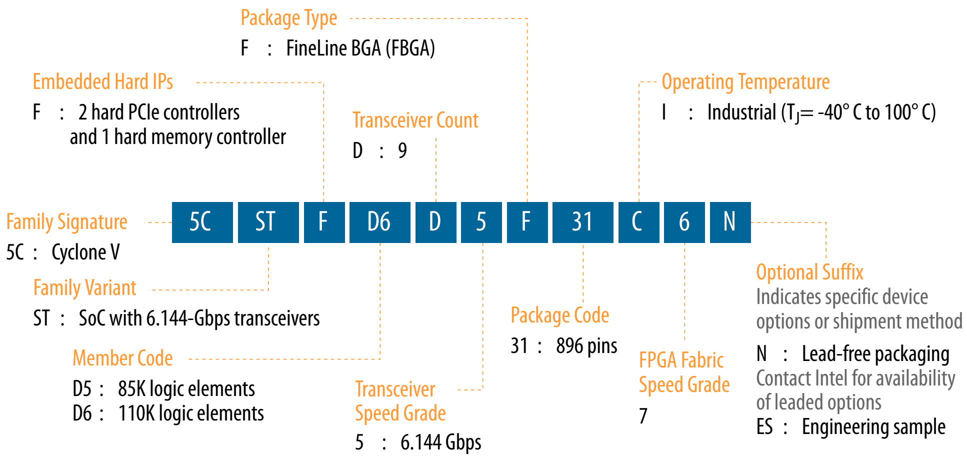
continued...

Related Information

Product Selector Guide
Provides the latest information about Intel products.

Available Options

Figure 6. Sample Ordering Code and Available Options for Cyclone V ST Devices



Maximum Resources

Table 14. Maximum Resource Counts for Cyclone V ST Devices

Resource		Member Code	
		D5	D6
Logic Elements (LE) (K)		85	110
ALM		32,070	41,910
Register		128,300	166,036
Memory (Kb)	M10K	3,970	5,570
	MLAB	480	621
Variable-precision DSP Block		87	112
18 x 18 Multiplier		174	224
FPGA PLL		6	6
HPS PLL		3	3
6.144 Gbps Transceiver		9	9
FPGA GPIO(10)		288	288
HPS I/O		181	181
LVDS	Transmitter	72	72

continued...

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(10) The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

Resource		Member Code	
		D5	D6
	Receiver	72	72
PCIe Hard IP Block		2	2
FPGA Hard Memory Controller		1	1
HPS Hard Memory Controller		1	1
Arm Cortex-A9 MPCore Processor		Dual-core	Dual-core

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices
Provides the number of LVDS channels in each device package.

Package Plan

Table 15. Package Plan for Cyclone V ST Devices

- The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.
- Transceiver counts shown are for transceiver ≤5 Gbps . 6 Gbps transceiver channel count support depends on the package and channel usage. For more information about the 6 Gbps transceiver channel count, refer to the *Cyclone V Device Handbook Volume 2: Transceivers*.

Member Code	F896 (31 mm)		
	FPGA GPIO	HPS I/O	XCVR
D5	288	181	9 (11)
D6	288	181	9 (11)

Related Information

6.144-Gbps Support Capability in Cyclone V GT Devices, Cyclone V Device Handbook Volume 2: Transceivers
Provides more information about 6 Gbps transceiver channel count.

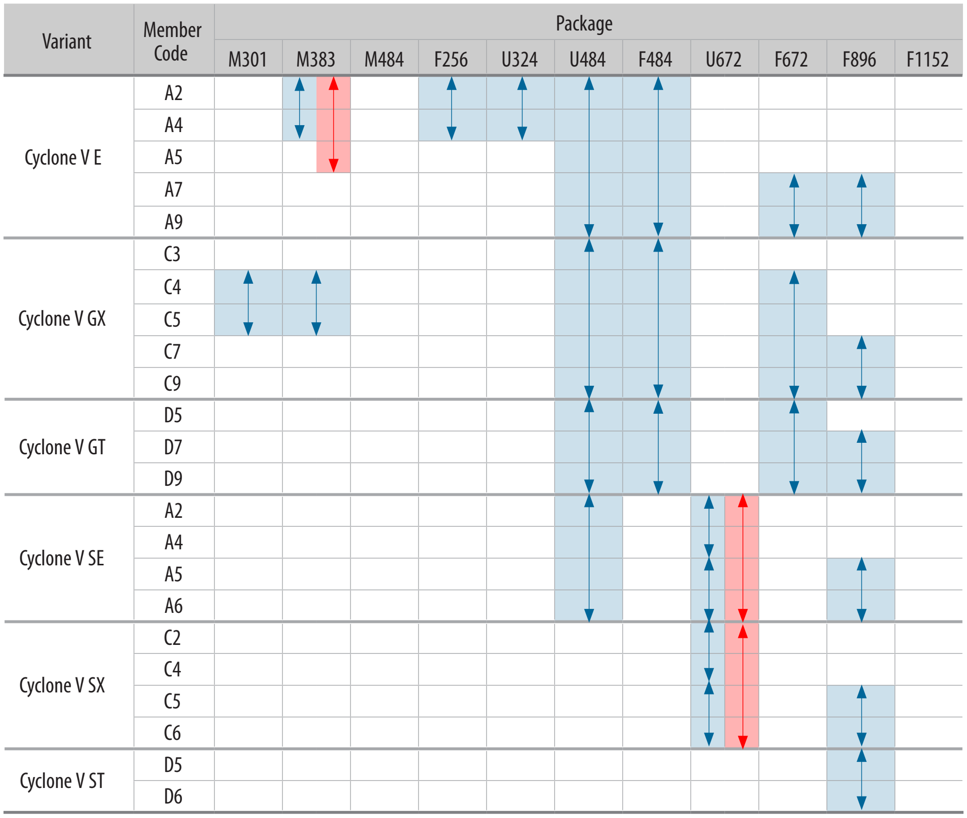
---

(11) If you require CPRI (at 4.9152 Gbps) and PCIe Gen2 transmit jitter compliance, Intel recommends that you use only up to seven full-duplex transceiver channels for CPRI, and up to six full-duplex channels for PCIe Gen2. The CMU channels are not considered full-duplex channels.

I/O Vertical Migration for Cyclone V Devices

Figure 7. Vertical Migration Capability Across Cyclone V Device Packages and Densities

The arrows indicate the vertical migration paths. The devices included in each vertical migration path are shaded. You can also migrate your design across device densities in the same package option if the devices have the same dedicated pins, configuration pins, and power pins.



Variant	Member Code	Package										
		M301	M383	M484	F256	U324	U484	F484	U672	F672	F896	F1152
Cyclone V E	A2		▨ 🟥		▨	▨	▨	▨				
	A4		▨ 🟥		▨	▨	▨	▨				
	A5		🟥				▨	▨				
	A7						▨	▨		▨	▨	
	A9						▨	▨		▨	▨	
Cyclone V GX	C3						▨	▨				
	C4	▨	▨				▨	▨		▨		
	C5	▨	▨				▨	▨		▨		
	C7						▨	▨		▨	▨	
	C9						▨	▨		▨	▨	
Cyclone V GT	D5						▨	▨		▨		
	D7						▨	▨		▨	▨	
	D9						▨	▨		▨	▨	
Cyclone V SE	A2						▨		▨ 🟥			
	A4						▨		▨ 🟥			
	A5						▨		▨ 🟥		▨	
	A6						▨		▨ 🟥		▨	
Cyclone V SX	C2								▨ 🟥			
	C4								▨ 🟥			
	C5								▨ 🟥		▨	
	C6								▨ 🟥		▨	
Cyclone V ST	D5										▨	
	D6										▨	

You can achieve the vertical migration shaded in red if you use only up to 175 GPIOs for the M383 package, and 138 GPIOs for the U672 package. These migration paths are not shown in the Intel Quartus Prime software Pin Migration View.

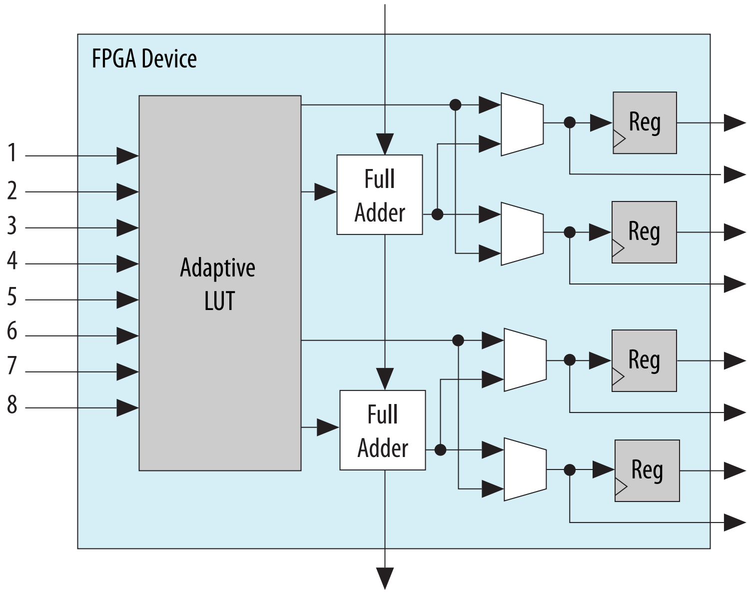
Note: To verify the pin migration compatibility, use the Pin Migration View window in the Intel Quartus Prime software Pin Planner.

Adaptive Logic Module

Cyclone V devices use a 28 nm ALM as the basic building block of the logic fabric.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than previous generations.

Figure 8. ALM for Cyclone V Devices



You can configure up to 25% of the ALMs in the Cyclone V devices as distributed memory using MLABs.

Related Information

Embedded Memory Capacity in Cyclone V Devices on page 21
Lists the embedded memory capacity for each device.

Variable-Precision DSP Block

Cyclone V devices feature a variable-precision DSP block that supports these features:

- Configurable to support signal processing precisions ranging from 9 x 9, 18 x 18 and 27 x 27 bits natively
- A 64-bit accumulator
- A hard preadder that is available in both 18- and 27-bit modes
- Cascaded output adders for efficient systolic finite impulse response (FIR) filters
- Internal coefficient register banks, 8 deep, for each multiplier in 18- or 27-bit mode
- Fully independent multiplier operation
- A second accumulator feedback register to accommodate complex multiply-accumulate functions
- Fully independent Efficient support for single-precision floating point arithmetic
- The inferability of all modes by the Intel Quartus Prime design software

PLL Features

The PLLs in the Cyclone V devices support the following features:

- Frequency synthesis
- On-chip clock deskew
- Jitter attenuation
- Programmable output clock duty cycles
- PLL cascading
- Reference clock switchover
- Programmable bandwidth
- User-mode reconfiguration of PLLs
- Low power mode for each fractional PLL
- Dynamic phase shift
- Direct, source synchronous, zero delay buffer, external feedback, and LVDS compensation modes

Fractional PLL

In addition to integer PLLs, the Cyclone V devices use a fractional PLL architecture. The devices have up to eight PLLs, each with nine output counters. You can use the output counters to reduce PLL usage in two ways:

- Reduce the number of oscillators that are required on your board by using fractional PLLs
- Reduce the number of clock pins that are used in the device by synthesizing multiple clock frequencies from a single reference clock source

If you use the fractional PLL mode, you can use the PLLs for precision fractional-N frequency synthesis—removing the need for off-chip reference clock sources in your design.

The transceiver fractional PLLs that are not used by the transceiver I/Os can be used as general purpose fractional PLLs by the FPGA fabric.

FPGA General Purpose I/O

Cyclone V devices offer highly configurable GPIOs. The following list describes the features of the GPIOs:

- Programmable bus hold and weak pull-up
- LVDS output buffer with programmable differential output voltage (V_{OD}) and programmable pre-emphasis
- On-chip parallel termination (R_T OCT) for all I/O banks with OCT calibration to limit the termination impedance variation
- On-chip dynamic termination that has the ability to swap between series and parallel termination, depending on whether there is read or write on a common bus for signal integrity
- Easy timing closure support using the hard read FIFO in the input register path, and delay-locked loop (DLL) delay chain with fine and coarse architecture

External Memory Performance

Table 20. External Memory Interface Performance in Cyclone V Devices

The maximum and minimum operating frequencies depend on the memory interface standards and the supported delay-locked loop (DLL) frequency listed in the device datasheet.

Interface	Voltage (V)	Maximum Frequency (MHz)		Minimum Frequency (MHz)
		Hard Controller	Soft Controller	
DDR3 SDRAM	1.5	400	303	303
	1.35	400	303	303
DDR2 SDRAM	1.8	400	300	167
LPDDR2 SDRAM	1.2	333	300	167

Related Information

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Intel's External Memory Interface Spec Estimator tool.

HPS External Memory Performance

Table 21. HPS External Memory Interface Performance

The hard processor system (HPS) is available in Cyclone V SoC devices only.

Interface	Voltage (V)	HPS Hard Controller (MHz)
DDR3 SDRAM	1.5	400
	1.35	400
DDR2 SDRAM	1.8	400
LPDDR2 SDRAM	1.2	333

Related Information

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Intel's External Memory Interface Spec Estimator tool.

Low-Power Serial Transceivers

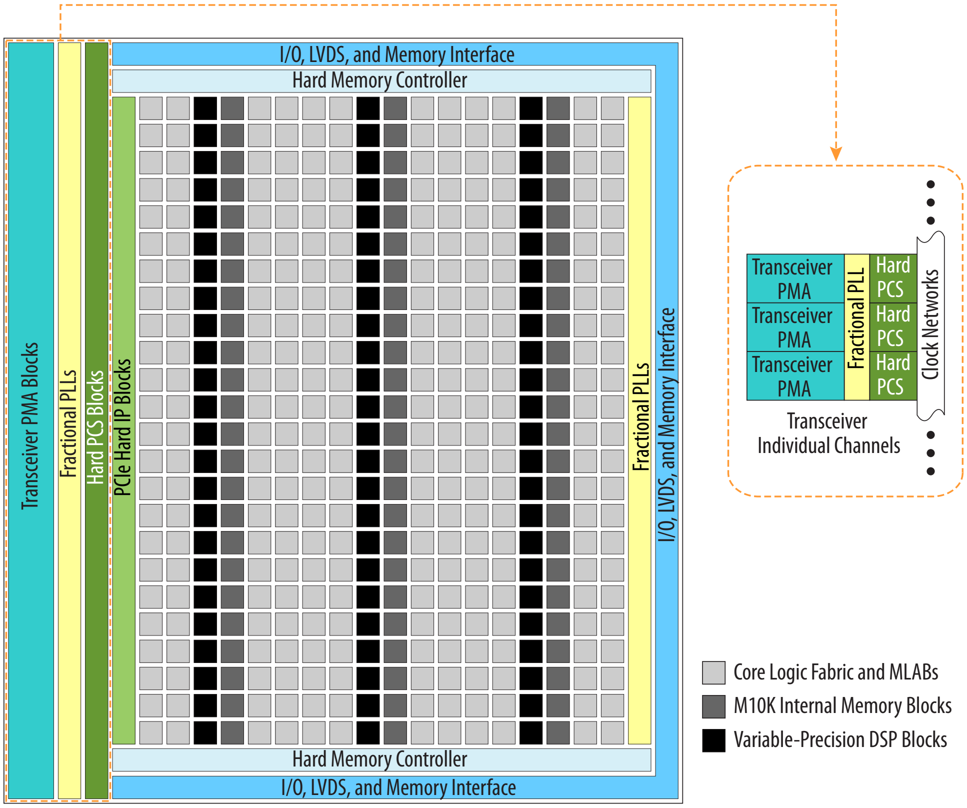
Cyclone V devices deliver the industry’s lowest power 6.144 Gbps transceivers at an estimated 88 mW maximum power consumption per channel. Cyclone V transceivers are designed to be compliant with a wide range of protocols and data rates.

Transceiver Channels

The transceivers are positioned on the left outer edge of the device. The transceiver channels consist of the physical medium attachment (PMA), physical coding sublayer (PCS), and clock networks.

Figure 10. Device Chip Overview for Cyclone V GX and GT Devices

The figure shows a Cyclone V FPGA with transceivers. Different Cyclone V devices may have a different floorplans than the one shown here.



PMA Features

To prevent core and I/O noise from coupling into the transceivers, the PMA block is isolated from the rest of the chip—ensuring optimal signal integrity. For the transceivers, you can use the channel PLL of an unused receiver PMA as an additional transmit PLL.

Table 22. PMA Features of the Transceivers in Cyclone V Devices

Features	Capability
Backplane support	Driving capability up to 6.144 Gbps
PLL-based clock recovery	Superior jitter tolerance
Programmable deserialization and word alignment	Flexible deserialization width and configurable word alignment pattern
Equalization and pre-emphasis	• Up to 14.37 dB of pre-emphasis and up to 4.7 dB of equalization • No decision feedback equalizer (DFE)
Ring oscillator transmit PLLs	614 Mbps to 6.144 Gbps
Input reference clock range	20 MHz to 400 MHz
Transceiver dynamic reconfiguration	Allows the reconfiguration of a single channel without affecting the operation of other channels

PCS Features

The Cyclone V core logic connects to the PCS through an 8, 10, 16, 20, 32, or 40 bit interface, depending on the transceiver data rate and protocol. Cyclone V devices contain PCS hard IP to support PCIe Gen1 and Gen2, Gbps Ethernet (GbE), Serial RapidIO® (SRIO), and Common Public Radio Interface (CPRI).

Most of the standard and proprietary protocols from 614 Mbps to 6.144 Gbps are supported.

Table 23. Transceiver PCS Features for Cyclone V Devices

PCS Support	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
3-Gbps and 6-Gbps Basic	0.614 to 6.144	• Phase compensation FIFO • Byte serializer • 8B/10B encoder • Transmitter bit-slip	• Word aligner • Deskew FIFO • Rate-match FIFO • 8B/10B decoder • Byte deserializer • Byte ordering • Receiver phase compensation FIFO
PCIe Gen1 (x1, x2, x4)	2.5 and 5.0	• Dedicated PCIe PHY IP core • PIPE 2.0 interface to the core logic	• Dedicated PCIe PHY IP core • PIPE 2.0 interface to the core logic
PCIe Gen2 (x1, x2, x4)(12)			
GbE	1.25	• Custom PHY IP core with preset feature • GbE transmitter synchronization state machine	• Custom PHY IP core with preset feature • GbE receiver synchronization state machine
XAUI (13)	3.125	• Dedicated XAUI PHY IP core • XAUI synchronization state machine for bonding four channels	• Dedicated XAUI PHY IP core • XAUI synchronization state machine for realigning four channels
HiGig	3.75		
SRIO 1.3 and 2.1	1.25 to 3.125	• Custom PHY IP core with preset feature • SRIO version 2.1-compliant x2 and x4 channel bonding	• Custom PHY IP core with preset feature • SRIO version 2.1-compliant x2 and x4 deskew state machine
SDI, SD/HD, and 3G-SDI	0.27(14), 1.485, and 2.97	Custom PHY IP core with preset feature	Custom PHY IP core with preset feature
JESD204A	0.3125(15) to 3.125		

continued...

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(12) PCIe Gen2 is supported for Cyclone V GT and ST devices. The PCIe Gen2 x4 support is PCIe-compatible.

(13) XAUI is supported through the soft PCS.

(14) The 0.27-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.

(15) The 0.3125-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.

PCS Support	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
Serial ATA Gen1 and Gen2	1.5 and 3.0	• Custom PHY IP core with preset feature • Electrical idle	• Custom PHY IP core with preset feature • Signal detect • Wider spread of asynchronous SSC
CPRI 4.1(16)	0.6144 to 6.144	• Dedicated deterministic latency PHY IP core • Transmitter (TX) manual bit-slip mode	• Dedicated deterministic latency PHY IP core • Receiver (RX) deterministic latency state machine
OBSAI RP3	0.768 to 3.072		
V-by-One HS	Up to 3.75	Custom PHY IP core	• Custom PHY IP core • Wider spread of asynchronous SSC
DisplayPort 1.2(17)	1.62 and 2.7		

SoC with HPS

Each SoC combines an FPGA fabric and an HPS in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

HPS Features

The HPS consists of a dual-core Arm Cortex-A9 MPCore processor, a rich set of peripherals, and a shared multiport SDRAM memory controller, as shown in the following figure.

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(16) High-voltage output mode (1000-BASE-CX) is not supported.

(17) Pending characterization.

HPS–FPGA AXI Bridges

The HPS–FPGA bridges, which support the Advanced Microcontroller Bus Architecture (AMBA®) Advanced eXtensible Interface (AXI™) specifications, consist of the following bridges:

- FPGA-to-HPS AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the FPGA fabric to issue transactions to slaves in the HPS.
- HPS-to-FPGA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the HPS to issue transactions to slaves in the FPGA fabric.
- Lightweight HPS-to-FPGA AXI bridge—a lower latency 32 bit width bus that allows the HPS to issue transactions to slaves in the FPGA fabric. This bridge is primarily used for control and status register (CSR) accesses to peripherals in the FPGA fabric.

The HPS–FPGA AXI bridges allow masters in the FPGA fabric to communicate with slaves in the HPS logic, and vice versa. For example, the HPS-to-FPGA AXI bridge allows you to share memories instantiated in the FPGA fabric with one or both microprocessors in the HPS, while the FPGA-to-HPS AXI bridge allows logic in the FPGA fabric to access the memory and peripherals in the HPS.

Each HPS–FPGA bridge also provides asynchronous clock crossing for data transferred between the FPGA fabric and the HPS.

HPS SDRAM Controller Subsystem

The HPS SDRAM controller subsystem contains a multiport SDRAM controller and DDR PHY that are shared between the FPGA fabric (through the FPGA-to-HPS SDRAM interface), the level 2 (L2) cache, and the level 3 (L3) system interconnect. The FPGA-to-HPS SDRAM interface supports AMBA AXI and Avalon® Memory-Mapped (Avalon-MM) interface standards, and provides up to six individual ports for access by masters implemented in the FPGA fabric.

To maximize memory performance, the SDRAM controller subsystem supports command and data reordering, deficit round-robin arbitration with aging, and high-priority bypass features. The SDRAM controller subsystem supports DDR2, DDR3, or LPDDR2 devices up to 4 Gb in density operating at up to 400 MHz (800 Mbps data rate).

FPGA Configuration and Processor Booting

The FPGA fabric and HPS in the SoC are powered independently. You can reduce the clock frequencies or gate the clocks to reduce dynamic power, or shut down the entire FPGA fabric to reduce total system power.

You can configure the FPGA fabric and boot the HPS independently, in any order, providing you with more design flexibility:

- You can boot the HPS independently. After the HPS is running, the HPS can fully or partially reconfigure the FPGA fabric at any time under software control. The HPS can also configure other FPGAs on the board through the FPGA configuration controller.
- You can power up both the HPS and the FPGA fabric together, configure the FPGA fabric first, and then boot the HPS from memory accessible to the FPGA fabric.

Note: Although the FPGA fabric and HPS are on separate power domains, the HPS must remain powered up during operation while the FPGA fabric can be powered up or down as required.

Related Information

Cyclone V Device Family Pin Connection Guidelines
Provides detailed information about power supply pin connection guidelines and power regulator sharing.

Hardware and Software Development

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Platform Designer (Standard) system integration tool in the Intel Quartus Prime software.

For software development, the Arm-based SoC devices inherit the rich software development ecosystem available for the Arm Cortex-A9 MPCore processor. The software development process for Intel SoCs follows the same steps as those for other SoC devices from other manufacturers. Support for Linux, VxWorks®, and other operating systems is available for the SoCs. For more information on the operating systems support availability, contact the Intel sales team.

You can begin device-specific firmware and software development on the Intel SoC Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board that runs on a PC. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.

Related Information

International Altera Sales Support Offices

Dynamic and Partial Reconfiguration

The Cyclone V devices support dynamic reconfiguration and partial reconfiguration.

Dynamic Reconfiguration

The dynamic reconfiguration feature allows you to dynamically change the transceiver data rates, PMA settings, or protocols of a channel, without affecting data transfer on adjacent channels. This feature is ideal for applications that require on-the-fly multiprotocol or multirate support. You can reconfigure the PMA and PCS blocks with dynamic reconfiguration.

Partial Reconfiguration

Note: The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Partial reconfiguration allows you to reconfigure part of the device while other sections of the device remain operational. This capability is important in systems with critical uptime requirements because it allows you to make updates or adjust functionality without disrupting services.

Power Management

Leveraging the FPGA architectural features, process technology advancements, and transceivers that are designed for power efficiency, the Cyclone V devices consume less power than previous generation Cyclone FPGAs:

- Total device core power consumption—less by up to 40%.
- Transceiver channel power consumption—less by up to 50%.

Additionally, Cyclone V devices contain several hard IP blocks that reduce logic resources and deliver substantial power savings of up to 25% less power than equivalent soft implementations.

Document Revision History for Cyclone V Device Overview

Document Version	Changes
2018.05.07	• Added the low power option ("L" suffix) for Cyclone V SE and Cyclone V SX devices in the *Sample Ordering Code and Available Options* diagrams. • Rebranded as Intel.

Date	Version	Changes
December 2017	2017.12.18	• Updated ALM resources for Cyclone V E, Cyclone V SE, Cyclone V SX, and Cyclone V ST devices.
June 2016	2016.06.10	Updated Cyclone V GT speed grade to –7 in Sample Ordering Code and Available Options for Cyclone V GT Devices diagram.
December 2015	2015.12.21	• Added descriptions to package plan tables for Cyclone V GT and ST devices. • Changed instances of *Quartus II* to *Quartus Prime*.
June 2015	2015.06.12	• Replaced a note to partial reconfiguration feature. Note: The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Altera sales representatives. • Updated logic elements (LE) (K) for the following devices: — Cyclone V E A7: Updated from 149.5 to 150 — Cyclone V GX C3: Updated from 35.5 to 36 — Cyclone V GX C7: Updated from 149.7 to 150 — Cyclone V GT D7: Updated from 149.5 to 150 • Updated MLAB (Kb) in Maximum Resource Counts for Cyclone V GX Devices table as follows: — Cyclone V GX C3: Updated from 291 to 182 — Cyclone V GX C4: Updated from 678 to 424 — Cyclone V GX C5: Updated from 678 to 424 — Cyclone V GX C7: Updated from 1,338 to 836 — Cyclone V GX C9: Updated from 2,748 to 1,717

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Date	Version	Changes
July 2014	2014.07.07	Updated the I/O vertical migration figure to clarify the migration capability of Cyclone V SE and SX devices.
December 2013	2013.12.26	• Corrected single or dual-core ARM Cortex-A9 MPCore processor-up to 925 MHz from 800 MHz. • Removed "Preliminary" texts from Ordering Code figures, Maximum Resources, Package Plan and I/O Vertical Migration tables. • Removed the note "The number of GPIOs does not include transceiver I/Os. In the Quartus II software, the number of user I/Os includes transceiver I/Os." for GPIOs in the Maximum Resource Counts table for Cyclone V E and SE. • Added link to Altera Product Selector for each device variant. • Updated Embedded Hard IPs for Cyclone V GT devices to indicate Maximum 2 hard PCIe and 2 hard memory controllers. • Added leaded package options. • Removed the note "The number of PLLs includes general-purpose fractional PLLs and transceiver fractional PLLs." for all PLLs in the Maximum Resource Counts table. • Corrected max LVDS counts for transmitter and receiver for Cyclone V E A5 device from 84 to 60. • Corrected max LVDS counts for transmitter and receiver for Cyclone V E A9 device from 140 to 120. • Corrected variable-precision DSP block, 27 x 27 multiplier, 18 x 18 multiplier adder mode and 18 x 18 multiplier adder summed with 36 bit input for Cyclone V SE devices from 58 to 84. • Corrected 18 x 18 multiplier for Cyclone V SE devices from 116 to 168. • Corrected 9 x 9 multiplier for Cyclone V SE devices from 174 to 252. • Corrected LVDS transmitter for Cyclone V SE A2 and A4 as well as SX C2 and C4 devices from 31 to 32. • Corrected LVDS receiver for Cyclone V SE A2 and A4 as well as SX C2 and C4 devices from 35 to 37. • Corrected transceiver speed grade for Cyclone V ST devices ordering code from 4 to 5. • Updated the DDR3 SDRAM for the maximum frequency's soft controller and the minimum frequency from 300 to 303 for voltage 1.35V. • Added links to Altera's External Memory Spec Estimator tool to the topics listing the external memory interface performance. • Corrected XAUI is supported through the soft PCS in the PCS features for Cyclone V. • Added decompression support for the CvP configuration mode.
May 2013	2013.05.06	• Added link to the known document issues in the Knowledge Base. • Moved all links to the Related Information section of respective topics for easy reference. • Corrected the title to the PCIe hard IP topic. Cyclone V devices support only PCIe Gen1 and Gen2. • Updated Supporting Feature in Table 1 of Increased bandwidth capacity to '6.144 Gbps'. • Updated Description in Table 2 of Low-power high-speed serial interface to '6.144 Gbps'. • Updated Description in Table 3 of Cyclone V GT to '6.144 Gbps'. • Updated the M386 package to M383 for Figure 1, Figure 2 and Figure 3. • Updated Figure 2 and Figure 3 for Transceiver Count by adding 'F : 4'. • Updated LVDS in the Maximum Resource Counts tables to include Transmitter and Receiver values. • Updated the package plan with M383 for the Cyclone V E device. • Removed the M301 and M383 packages from the Cyclone V GX C4 device. • Updated the GPIO count to '129' for the M301 package of the Cyclone V GX C5 device. • Updated 5 Gbps to '6.144 Gbps' forCyclone V GT device.

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